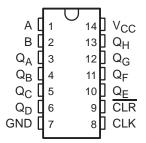
- EPIC™ (Enhanced-Performance Implanted CMOS) 2-µ Process
- Typical V_{OLP} (Output Ground Bounce)
 < 0.8 V at V_{CC}, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot)
 > 2 V at V_{CC}, T_A = 25°C
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JEDEC Standard JESD-17
- Package Options Include Plastic Small-Outline (D), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW), Ceramic Flat (W) Packages, Chip Carriers (FK), and (J) 300-mil DIPs

description

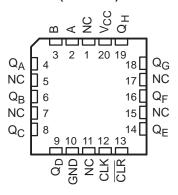
These 8-bit parallel-out serial shift registers are designed for 2.7-V to 5.5-V V_{CC} operation.

The 'LV164 feature AND-gated serial (A and B) inputs and an asynchronous clear (CLR) input. The gated serial inputs permit complete control over incoming data as a low at either input inhibits entry of the new data and resets the first flip-flop to the low level at the next clock pulse. A high-level

SN54LV164 . . . J OR W PACKAGE SN74LV164 . . . D, DB, OR PW PACKAGE (TOP VIEW)



SN54LV164 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

input enables the other input, which then determines the state of the first flip-flop. Data at the serial inputs can be changed while the clock is high or low, provided the minimum setup time requirements are met. Clocking occurs on the low-to-high-level transition of the clock (CLK) input.

The SN74LV164 is available in TI's shrink small-outline package (DB), which provides the same I/O pin count and functionality of standard small-outline packages in less than half the printed-circuit-board area.

The SN54LV164 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74LV164 is characterized for operation from –40°C to 85°C.



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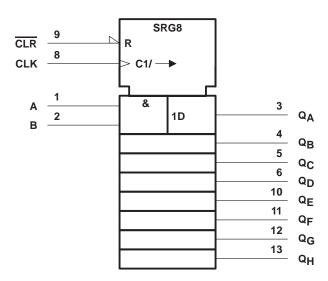
FUNCTION TABLE

	INPL	JTS	OUTPUTS				
CLR	CLK	Α	В	Q_{A}	Q _B .	Q _H	
L	Х	Χ	Х	L	L	L	
Н	L	Χ	X	Q _{A0}	Q_{B0}	Q_{H0}	
Н	\uparrow	Н	Н	Н	Q_{An}	Q_{Gn}	
Н	\uparrow	L	Χ	L	Q_{An}	Q_Gn	
Н	\uparrow	Χ	L	L	Q_{An}	Q_{Gn}	

 $\mathsf{Q}_{A0},\,\mathsf{Q}_{B0},\,\mathsf{Q}_{H0}$ = the level of $\mathsf{Q}_A,\,\mathsf{Q}_B,\,\mathsf{or}\,\,\mathsf{Q}_H,\,\mathsf{respectively},$ before the indicated steady-state inputs conditions were

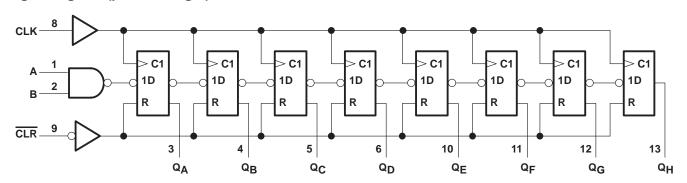
Q_{An}, Q_{Gn} = the level of Q_A or Q_G before the most recent ↑ transition of the clock: indicates a 1-bit shift

logic symbol†



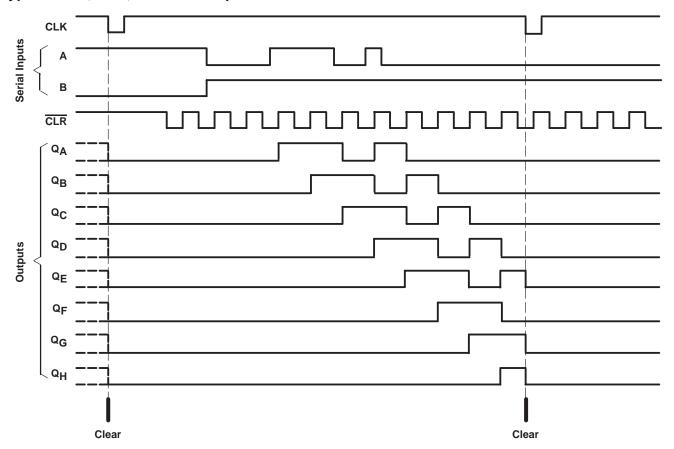
[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for D, DB, J, PW, and W packages.

logic diagram (positive logic)





typical clear, shift, and clear sequences



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} Input voltage range, V_{I} (see Note 1) Output voltage range, V_{O} (see Notes 1 and 2) Input clamp current, I_{IK} (V_{I} < 0 or V_{I} > V_{CC}) Output clamp current, I_{OK} (V_{O} < 0 or V_{O} > V_{CC}) Continuous output current, I_{O} (V_{O} = 0 to V_{CC}) Continuous current through V_{CC} or GND Maximum power dissipation at T_{A} = 55°C (in still air) (see Note 3): D package	$ \begin{array}{cccccccccccccccccccccccccccccccccccc$
Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note 3): D package	1.25 W
DB or PW packa Storage temperature range, T _{stg}	ge 0.5 W –65°C to 150°C
o i o i o i o i o i o i o i o i o i o i	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

- 2. This value is limited to 7 V maximum.
- 3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.



recommended operating conditions (see Note 4)

			SN54L	.V164	SN74LV164		UNIT
			MIN	MAX	MIN	MAX	UNII
Vcc	Supply voltage		2.7	5.5	2.7	5.5	V
\/	High level input valtage	V _{CC} = 2.7 V to 3.6 V	2		2		V
VIH	High-level input voltage	V _{CC} = 4.5 V to 5.5 V	3.15		3.15		V
\/	Low lovel input voltage	V _{CC} = 2.7 V to 3.6 V		0.8		0.8	V
VIL	Low-level input voltage	V _{CC} = 4.5 V to 5.5 V		1.65		1.65	V
٧ı	Input voltage		0	Vcc	0	VCC	V
۷o	Output voltage		0	VCC	0	VCC	V
1	High lovel output ourrent	V _{CC} = 2.7 V to 3.6 V	20	-6		-6	A
ЮН	High-level output current	V _{CC} = 4.5 V to 5.5 V	30	-12		-12	mA
	Low level output ourrent	V _{CC} = 2.7 V to 3.6 V	Q	6		6	mA
IOL	Low-level output current	V _{CC} = 4.5 V to 5.5 V		12		12	IIIA
Δt/Δν	Input transition rise or fall rate	-	0	100	0	100	ns/V
T _A	Operating free-air temperature		-55	125	-40	85	°C

NOTE 4: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	Voot	SN	54LV16	4	SN	174LV16	4	UNIT	
PARAMETER	TEST CONDITIONS	v _{cc} †	MIN	TYP	MAX	MIN	TYP	MAX	UNIT	
	I _{OH} = -100 μA	MIN to MAX	V _{CC} - 0	.2		VCC - C).2			
Voн	I _{OH} = -6 mA	3 V	2.4			2.4			V	
	I _{OH} = -12 mA	4.5 V	3.6			3.6				
	I _{OL} = 100 μA	MIN to MAX			0.2			0.2		
VOL	OL $IOL = 6 mA$ $3 V$			14	0.4			0.4	V	
	I _{OL} = 12 mA	4.5 V		FL	0.55			0.55		
1.	V _I = V _{CC} or GND	3.6 V		9	±1			±1		
1 ₁	ALE ACC OL GIAD	5.5 V		Ć)	±1			±1	μΑ	
loo	$V_1 = V_{CC}$ or GND, $I_0 = 0$	3.6 V	2		20			20	μΑ	
lcc	ALE ACC OLGIND, IO = 0	5.5 V	J.		20			20	μΑ	
∆ICC	One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND	3 V to 3.6 V			500			500	μА	
C.	V _I = V _{CC} or GND	3.3 V		2.5			2.5	·	n.E	
Ci	AL = ACC OL GIAD	5 V		3			3		pF	

[†] For conditions shown as MIN or MAX, use the appropriate values under recommended operating conditions.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

			V _{CC} =		V _{CC} =		VCC =	2.7 V	UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
fclock	Clock frequency		0	40	0	35	0	30	MHz
	Pulse duration	CLR low	14		16		18		no
t _W	ruise duration	CLK high or low	14	OD	16	~	18		ns
	Cotum time and data hadana CLIVA	Data	8	P.P.	10	6 bro	12		20
t _{su}	Setup time, data before CLK↑	CLR inactive	5	6,	6	<	7		ns
t _h	Hold time, data after CLK↑		3		3		3		ns

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

					SI	N74LV16	64		
			V _{CC} =		V _{CC} =		V _{CC} =	2.7 V	UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
fclock	Clock frequency		0	40	0	35	0	30	MHz
	Pulse duration	CLR low	14		16		18		no
t _W	Fulse duration	CLK high or low	14		16		18		ns
	Satura tima a data hafara CLIVA	Data	8		10		12		no
t _{su}	Setup time, data before CLK↑	CLR inactive	5		6		7		ns
t _h	Hold time, data after CLK↑		3		3		3		ns

switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

			SN54LV164								
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} =	5.5 V ±	0.5 V	V _{CC} =	3.3 V ±	0.3 V	V _{CC} =	2.7 V	UNIT
	(01)	(0011 01)	MIN	TYP	MAX	MIN	TYP	MAX	∴ MIN	MAX	
f _{max}			40	90	~0 ¹	35	75	201	30		MHz
t _{pd}	CLK	Q		10	20		14	26	71.	32	ns
^t PHL	CLR	Q		12	20		16	26		32	ns

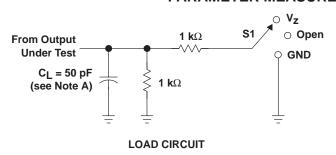
switching characteristics over recommended operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

			SN74LV164								
PARAMETER	FROM (INPUT)	TO (OUTPUT)	VCC =	5.5 V ±	0.5 V	VCC =	3.3 V \pm	0.3 V	VCC =	2.7 V	UNIT
	(1141 01)	(0011 01)	MIN	TYP	MAX	MIN	TYP	MAX	MIN	MAX	
fmax			40	90		35	75		30		MHz
t _{pd}	CLK	Q		10	20		14	26		32	ns
^t PHL	CLR	Q		12	20		16	26		32	ns

operating characteristics, $T_A = 25^{\circ}C$

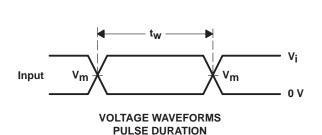
PARAMETER		TEST CONDITIONS	TYP	TYP	UNIT
Consul	Power dissipation capacitance	$C_1 = 50 \text{ pF}, f = 10 \text{ MHz}$	3.3 V	74	nE
Cpd	Fower dissipation capacitance	$C_L = 50 \text{ pr}, f = 10 \text{ MHz}$	5 V	75	p⊦

PARAMETER MEASUREMENT INFORMATION



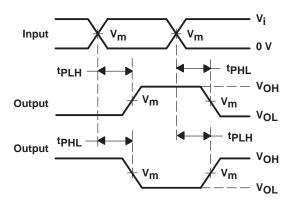
TEST	S1
tPLH/tPHL	Open
tPLZ/tPZL	Vz
tPHZ/tPZH	GND

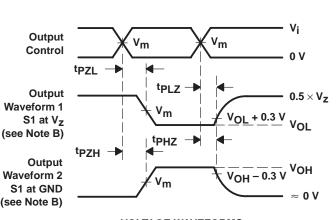
WAVEFORM CONDITION	V _{CC} = 4.5 V to 5.5 V	V _{CC} = 2.7 V to 3.6 V
٧ _m	0.5 × V _{CC}	1.5 V
Vi	VCC	2.7 V
Vz	2×V _{CC}	6 V



٧i **Timing Input** t_{SU} th ٧ $\boldsymbol{v_{m}}$ ٧m **Data Input** 0 V

VOLTAGE WAVEFORMS SETUP AND HOLD TIMES





VOLTAGE WAVEFORMS **PROPAGATION DELAY TIMES INVERTING AND NONINVERTING OUTPUTS**

VOLTAGE WAVEFORMS **ENABLE AND DISABLE TIMES** LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \ \Omega$, $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



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